



Material Content Data Sheet



Sales Product Name		BFR 181W H6327		Issued		29. August 2013		
MA#		MA000787820						
Package		PG-SOT323-3-1		Weight*		5.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.03		303	
	non noble metal	tin	7440-31-5	0.000	0.01		78	
	inorganic material	silicon	7440-21-3	0.013	0.22	0.26	2245	2626
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1324	
	non noble metal	copper	7440-50-8	2.617	43.96	44.14	439516	441369
wire	noble metal	gold	7440-57-5	0.007	0.12	0.12	1217	1217
encapsulation	organic material	carbon black	1333-86-4	0.032	0.53		5308	
	plastics	epoxy resin	-	0.680	11.41		114126	
	inorganic material	silicondioxide	60676-86-0	2.449	41.14	53.08	411385	530819
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22287	22287
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1682	1682
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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